

Features

- Super Low V_F Schottky rectifier
- Low profile, typical thickness 0.8mm
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Heatsink structure
- High temperature soldering guaranteed: 260°C/10 seconds



Package: iSGA
(SOD-123HS)



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	30	V
Maximum RMS Voltage	V_{RMS}	21	V
Maximum DC Blocking Voltage	V_{DC}	30	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.0	A
Peak Forward Surge Current 8.3ms Single Half Sine-wave Superimposed on Rated Load	I_{FSM}	30	A
Operating Junction and Storage Temperature Range	$T_J,$ T_{STG}	-55 to +150	$^\circ\text{C}$

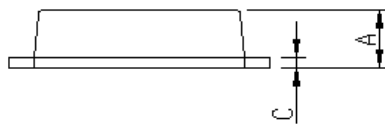
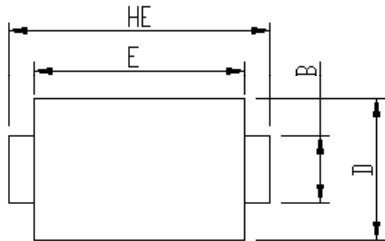
Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Test Conditions	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage	$I_F=1\text{A}, T_A=25^\circ\text{C}$	V_F	0.5	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$T_A=25^\circ\text{C}$	I_R	150	μA
	$T_A=125^\circ\text{C}$		15	mA
Typical Junction Capacitance	4.0 V, 1 MHz	C_J	80	pF
Typical Thermal Resistance ¹⁾	Junction to Ambient	$R_{\theta JA}$	75	$^\circ\text{C/W}$
	Junction to Case	$R_{\theta JC}$	55	
	Junction to Lead	$R_{\theta JL}$	15	

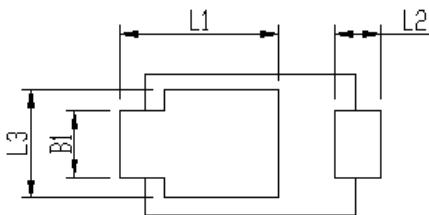
Note:1) The thermal resistance from junction to ambient, case or lead, mounted on FR-4 P.C.B

Package Outline Dimensions

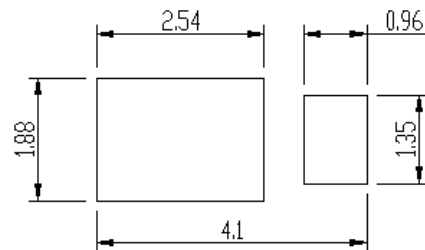
iSGA(SOD-123HS)



Package	iSGA(SOD-123HS)	
Unit:mm	MIN	MAX
A	0.75	0.90
B	0.85	1.05
B1	0.85	1.05
C	0.1	0.25
D	1.9	2.1
E	2.9	3.1
L1	2.0	2.45
L2	0.4	0.85
L3	1.3	1.7
HE	3.5	3.9



Soldering footprint



Package Information

Reel size	Quantity/reel	Quantity/inner Box	Quantity/Carton
7"	3K	30K	120K

Tape & Reel Specification

